

ABSTRACT

A method for analyzing defects on a substrate, including inspecting the substrate to detect the defects, identifying the defects by location, analyzing the defects to detect extended objects, and analyzing the extended objects for repetition across the substrate. Thus, the present invention extends beyond the present analysis methods, by analyzing
5 the extended objects for repetition across the substrate. In this manner, correlation with processing problems can be more readily detected, in cases where the individual defects themselves, of which the extended objects are formed, do not appear to have repeating properties.

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